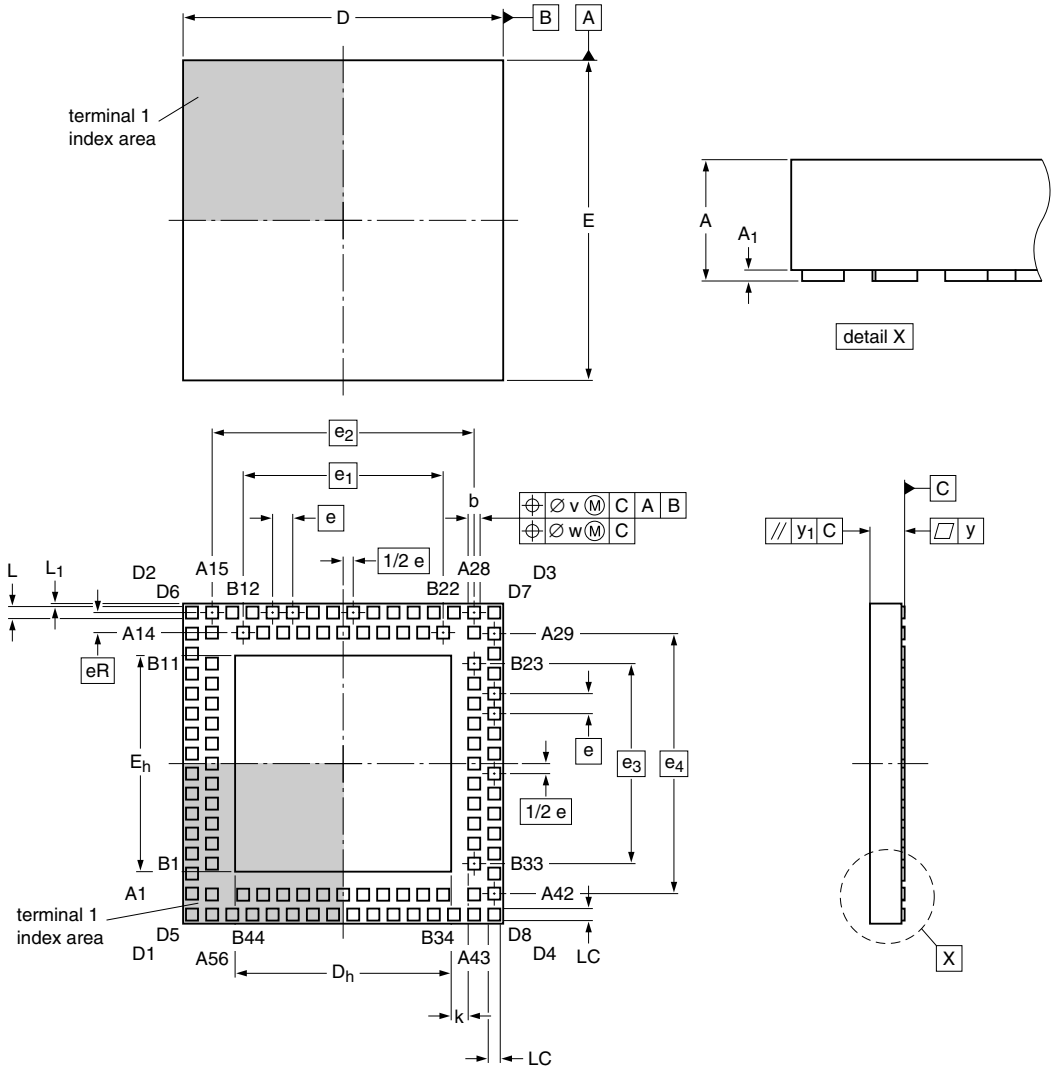
Package outline

HVQFN108U: plastic thermal enhanced very thin quad flat package; no leads; 108 terminals; low stand-off height; UTLP based; body 8 x 8 x 0.9 mm **SOT1032-3**



Dimensions

Unit		A	A_1	b	D	D_h	E	E_h	e	e_1	e_2	e_3	e_4	eR	k	L	L_1	LC	v	w	y	y_1
	max	1.00	0.05	0.35	8.05	5.45	8.05	5.45							0.475	0.35	0.10	0.35				
mm	nom	0.90	0.03	0.30	8.00	5.40	8.00	5.40	0.5	5	6.5	5	6.5	0.5	0.425	0.30	0.08	0.30	0.07	0.05	0.08	0.1
	min	0.85	0.00	0.25	7.95	5.35	7.95	5.35							0.375	0.25	0.05	0.25				

sot1032-3_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1032-3						~~08-03-05~~ 08-10-17

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